BAS40-06LT1

Preferred Device

Common Anode Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

- Extremely Fast Switching Speed
- Low Forward Voltage

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	40	V
THERMAL CHARACTERISTICS			
Characteristic	Symbol	Мах	Unit

	-		
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	225 1.8	mW mW/°C
Operating Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C
Forward Continuous Current	I _{FM}	120	mA
$ \begin{array}{ll} \mbox{Single Forward Current} & t \leq 1 \ s \\ t \leq 10 \ ms \end{array} $	I _{FSM}	200 600	mA
Thermal Resistance Junction-to-Ambient	$R_{\theta J A}$	508 (Note 1) 311 (Note 2)	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 @ minimum pad.

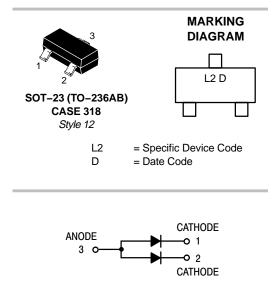
2. FR-4 @ 1.0 x 1.0 in pad.



ON Semiconductor®

http://onsemi.com

40 VOLTS SCHOTTKY BARRIER DIODE



ORDERING INFORMATION

	Device	Package	Shipping†
В	AS40-06LT1	SOT-23	3000 / Tape & Reel

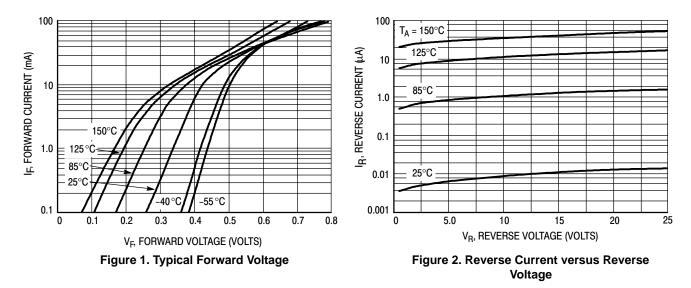
⁺For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

BAS40-06LT1

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
Reverse Breakdown Voltage	(I _R = 10 μA)	V _{(BR)R}	40	-	V
Total Capacitance	(V _R = 1.0 V, f = 1.0 MHz)	CT	-	5.0	pF
Reverse Leakage	(V _R = 25 V)	Ι _R	-	1.0	μAdc
Forward Voltage	(I _F = 1.0 mAdc)	V _F	-	380	mVdc
Forward Voltage	(I _F = 10 mAdc)	V _F	-	500	mVdc
Forward Voltage	(I _F = 40 mAdc)	V _F	-	1.0	Vdc



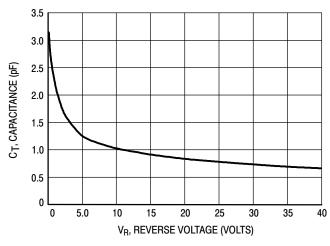
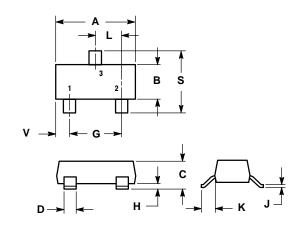


Figure 3. Typical Capacitance

PACKAGE DIMENSIONS

SOT-23 (TO-236)

CASE 318-08 ISSUE AH



NOTES:

 I. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.

 CONTROLLING DIMENSION: INCH.
MAXIUMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD

- LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 318-01, -02, AND -06 OBSOLETE, NEW STANDARD 318-09.

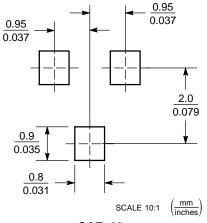
	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0385	0.0498	0.99	1.26
D	0.0140	0.0200	0.36	0.50
G	0.0670	0.0826	1.70	2.10
Н	0.0040	0.0098	0.10	0.25
J	0.0034	0.0070	0.085	0.177
Κ	0.0180	0.0236	0.45	0.60
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.0984	2.10	2.50
٧	0.0177	0.0236	0.45	0.60

STYLE 8: PIN 1. ANODE

2. NO CONNECTION

3. CATHODE

SOLDERING FOOTPRINT*



SOT-23

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters, including "Typicals" must be validated for each customer applications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to rusport or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850 ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.